

‘₹25K cr semiconductor packaging plant in Assam soon’



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Union Minister of State for Electronics and Information Technology Rajeev Chandrasekhar (*pictured*) on Thursday announced an upcoming semiconductor packaging facility in Assam with an outlay of ₹25,000 crore and said that the proposal from Tatas was under consideration.

“I want to share with you

today that Assam is soon going to have a ₹25,000 crore semiconductor packaging plant in the state. It is a proposal from the Tatas that has to be evaluated,” he added. Chandrasekhar was talking at the Digital India Future Skills summit in Guwahati.

In December last year, Assam Chief Minister Himanta Biswa Sarma had revealed Tata group’s investment plans for a semiconductor facility in the state.

In a post, Sarma had said, “Tata Group has submitted an application to set up a semiconductor processing plant in Assam with an investment of ₹40,000 crore. This will be a game changer.”

The investment announcement came after the state Cabinet approved a semiconductor policy last August.

Chandrasekhar made the announcement during his address at the first edition of the Digital India Future Skills

Summit being held in collaboration between the Ministry of Electronics and Information Technology (MeitY) and the National Institute of Electronics and Information Technology (NIELIT), in Guwahati.

The one-day summit is expected to see participation from over 1,000 delegates and attendees including prominent industry leaders, experts, and people from academia.